

## Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications



## Mechanical data

- Case: SOD-128
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz

### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

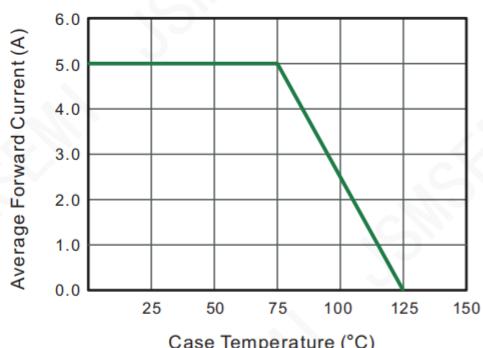
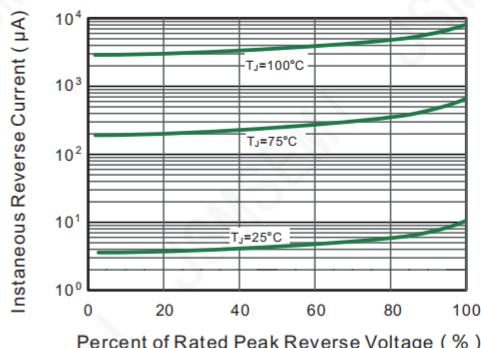
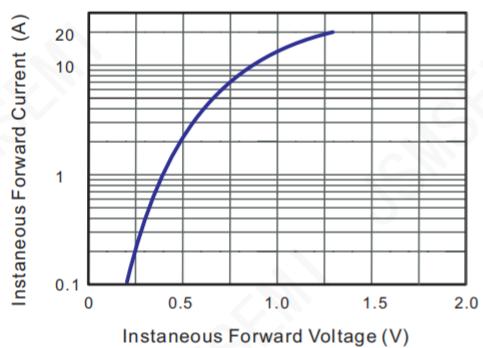
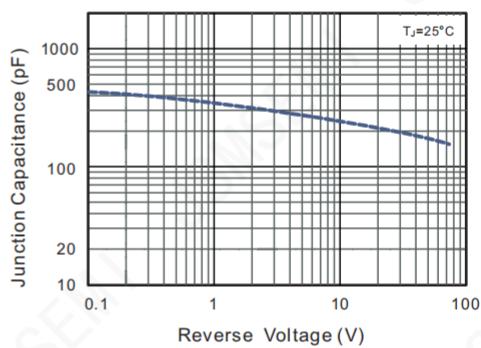
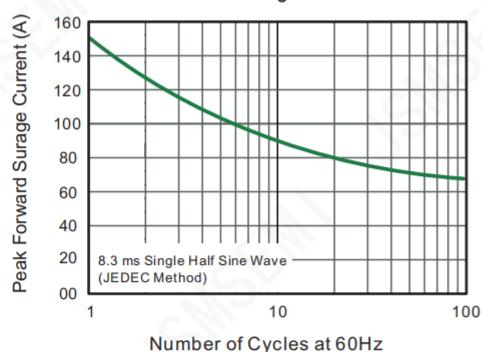
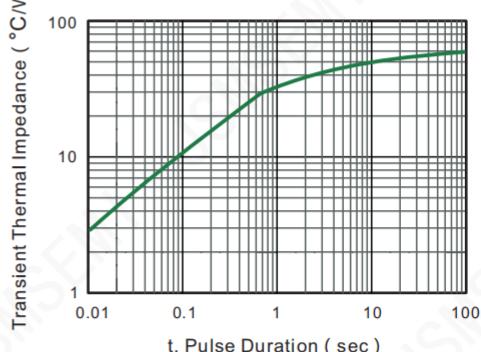
## Absolute Maximum Ratings and Electrical characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	PMEG6045ETPX-JSM	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	60	V
Maximum RMS voltage	$V_{RMS}$	42	V
Maximum DC Blocking Voltage	$V_{DC}$	60	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	150	A
Max Instantaneous Forward Voltage at 5 A	$V_F$	0.70	V
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Reverse Voltage $T_a = 100^\circ C$	$I_R$	1.0 50	mA
Typical Junction Capacitance <sup>(1)</sup>	$C_J$	300	pF
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$	60	°C/W
Operating Junction Temperature Range	$T_j$	-55 ~ +125	°C
Storage Temperature Range	$T_{stg}$	-55 ~ +150	°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

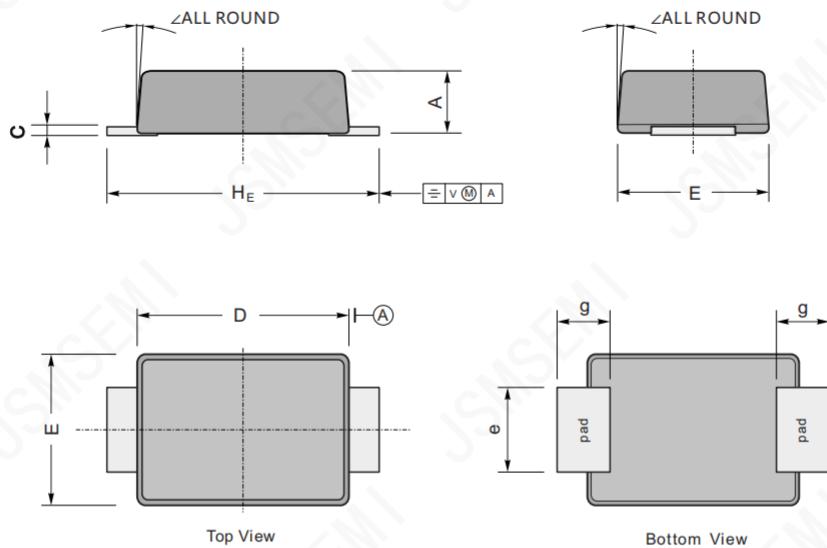
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

**Fig.1 Forward Current Derating Curve**

**Fig.2 Typical Reverse Characteristics**

**Fig.3 Typical Forward Characteristic**

**Fig.4 Typical Junction Capacitance**

**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

**Fig.6- Typical Transient Thermal Impedance**


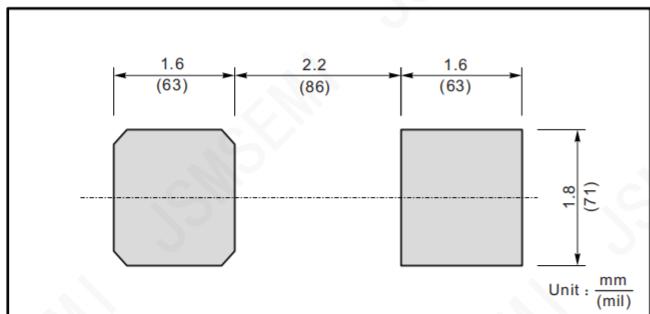
**PACKAGE OUTLINE**

Plastic surface mounted package; 2 leads

SOD-128



UNIT		A	C	D	E	e	g	H <sub>E</sub>	∠
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	7°
	min	35	4.7	130	94	51	31	173	

**The recommended mounting pad size**


## Revision History

Rev.	Change	Date
V1.0	Initial version	6/27/2021

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